REMARKS

Reconsideration of the Application is respectfully requested.

I. Claim Status

Claims 1-9 are currently pending and stand rejected.

No new matter has been added.

II. Specification Rejection

The Examiner objects to the disclosure because the text within the boxes for DAPE and for PMDA appears to be partially obliterated. Applicant includes a new chart with readable text to correct this rejection.

III. Claim Rejections

a) 35 U.S.C. § 112, first paragraph

Claims 1-9 stand rejected under 35 U.S.C. § 112, first paragraph as failing to comply with the enablement requirement. Specifically, the Examiner contends that while claim 1 claims that the polyimide precursor is imidized by heating, paragraph (0032) states that the adhesive aid composition is imidized by heating and that these two statements contradict each other.

Applicant respectfully traverses the rejection.

After reviewing the specification, Applicant has determined that the paragraph cited by the Examiner, paragraph (0032), was not properly translated. A new translation and certification have been presented. Newly translated paragraph (0032) reads:

> In a method for using the adhesive aid composition of the present invention, preferably, the polyimide precursor solution is applied to a substrate so that an imide film has a desired thickness, and dried at 50°C to 150°C for 50 to 180 minutes to

prepare a polyimide precursor film. **On top of that,** the adhesive aid composition of the present invention is applied to the precursor film, dried at 50°C to 150°C for 5 to 180 minutes, and then **the polyimide precursor is** subjected to imidization by heating at 200°C to 500°C for 20 to 300 minutes in a nitrogen stream to prepare a surface-adhesive film. In a system containing the polyimide precursor, a catalyst and a dehydrator, imidization can be performed at a lower temperature or within a shorter time. The resultant film of the present invention is used together with the substrate or after being separated from the substrate.

(emphasis added). Based on this new paragraph, it is clear that only the polyimide precursor is imidized by heating and that claim 1 is fully enabled. Therefore the Examiner's rejection is moot and Applicant's invention stands in condition for allowance.

b) 35 U.S.C. § 112, second paragraph

Claims 3 and 9 stand rejected under 35 U.S.C. § 112, second paragraph as being indefinite for failing to particularly point out and distinctly claim the subject matter which Applicant regards as the invention. Specifically, the Examiner contends that in claims 3 and 9 the polyimide precursor is heated but from the specification it seems that both the precursor and the adhesive aid composition are heated.

Applicant respectfully traverses the rejection.

As noted above, newly translated paragraph (0032) now clearly states that only the polyimide precursor is heated and subjected to imidization. Therefore the Examiner's rejection is moot and Applicant's invention stands in condition for allowance.

CONCLUSION

In view of the above remarks, it is respectfully requested that the application be reconsidered and that all pending claims be allowed and the case passed to issue.

If there are any other issues remaining, which the Examiner believes could be resolved through either a Supplemental Response or an Examiner's Amendment, the Examiner is respectfully requested to contact the undersigned at the telephone number indicated below.

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Respectfully submitted,

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